CLAIMS

1. An electroplating method, comprising:
placing a wafer into contact with liquid electrolyte in a vessel;
conducting ionic current through the liquid electrolyte;
moving an agitator below the wafer with a horizontal movement that selectively shields a portion of the wafer; and
rotating the wafer and synchronizing the rotation of the wafer with the movement of the agitator.

2. The method of claim 1 with the agitator having an array of ribs and slots, and with a first side of the agitator having fewer slots than a second side of the agitator.

3. The method of claim 1 with the agitator having an array of ribs and slots, and with the slots on a first side of the agitator shorter than the slots on a second side of the agitator.

4. An electroplating method, comprising:
placing a wafer into contact with liquid electrolyte in a vessel;
conducting ionic current through the liquid electrolyte;
moving an agitator below the wafer with a movement that selectively shields a portion of the wafer;
with the agitator having a stagger movement so that the time-averaged presence of a first side of the agitator over a first side of the wafer is greater than over a second side of the wafer.

5. The method of claim 4 with the agitator having an array of ribs and slots, and with a first side of the agitator having fewer slots than a second side of the agitator.

6. The method of claim 4 with the agitator having an array of ribs and slots, and with the slots on a first side of the agitator shorter than the slots on a second side of the agitator.

7. An electroplating method, comprising:
placing a wafer into contact with liquid electrolyte in a vessel;
conducting ionic current through the liquid electrolyte;
moving an agitator below the wafer with a movement that selectively shields a portion of the wafer;
with the agitator having an array of ribs, a top side, a bottom side, a first side and a second side, and with the first side of the agitator having fewer ribs than the second side of the agitator.

8. The method of claim 7 further including rotating the wafer and synchronizing the rotation of the wafer with the movement of the agitator.

9. The method of claim 7 with the ribs on the first side of the agitator shorter than the ribs on the second side of the agitator.